

ALPHA[®] TELECORE PLUS NO-CLEAN WIRE SOLDER

GENERAL DESCRIPTION

ALPHA Telecore Plus is a low residue core solder designed for no-clean soldering applications that must meet all appropriate Bellcore specifications. The unique blend of rosin and proprietary activators provide rapid wetting while leaving minimal, optically clear, completely inert residue.

USES

ALPHA Telecore Plus is suitable for use in any commercial no-clean hand soldering application that must meet Bellcore Specification TR-NWT-000078.

ALPHA Telecore Plus' activator system is effective in soldering to mildly oxidized surfaces of the following metals:

Cadmium (Plate)	Solder (Plate)
Copper	Solder (Hot Dip)
Gold	Tin (Hot Dip)
Silver	Tin (Plate)

RESIDUE REMOVAL

ALPHA Telecore Plus residues can be safely left on the board per Bellcore Specification TR-NWT-000078. If required, residues can be readily removed using Alpha solvents, saponifiers or semi-aqueous cleaners.

COMPANION LIQUID FLUX PRODUCT

If you choose to use a companion liquid flux, **NR205** is recommended in order to provide the optimal combination of high long-term reliability and low residue level. **NR205 is available in Alpha's Write Flux flux pens for precise flux application.**

TECHNICAL SPECIFICATIONS

Physical Properties	Typical Values
Softening Point	71°C (160°F)
Rosin Grade	WW per Fed. Spec. LLL-R-626
Water Extract Resistivity	40,000 ohm-cm, typical
Corrosiveness	Passes Copper Mirror; Passes IPC-SF-818 Copper Corrosion for Type L
Halide Content	Passes Silver Chromate Paper Test
Surface Insulation Resistance	Passes IPC-SF-818, Class III, Meets Bellcore Spec. TR-NWT-000078, Issue 3
Electromigration	Passes visual and electrical
J-STD-004 Classification	ROL0
IPC-SF-818	L3CN
ISO 12224	1.1.2

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AVAILABILITY

Alloy Description	Flux Loading	Wire Diameter
63Sn/37Pb	P1 or P2 (1.1% and 2.2% nominal)	.010 to .125 (Spool Weight 1 and 5 Lbs)
62Sn/36Pb/2Ag	P1 or P2 (1.1% and 2.2% nominal)	.010 to .125 (Spool Weight 1 and 5 Lbs)
96.5Sn/3.5Ag	P2 or P3 (2.2% and 3.3% nominal)	.010 to .125 (Spool Weight 1 and 5 Lbs)
Vaculoy 96.5Sn/3.0Ag/0.5Cu (SAC305)	P2 or P3 (2.2% and 3.3% nominal)	.010 to .125 (Spool Weight 1 and 5 Lbs)
99.3Sn/0.7Cu	P2 or P3 (2.2% and 3.3% nominal)	.010 to .125 (Spool Weight 1 and 5 Lbs)
Vaculoy SACX0307	P2 or P3 (2.2% and 3.3% nominal)	.010 to .125 (Spool Weight 1 and 5 Lbs)

HEALTH AND SAFETY

Telecore Plus is not considered toxic; however, its use in typical soldering processes will generate a certain amount of decomposition and reaction product fumes. These fumes must be adequately exhausted for operator safety and comfort. Please refer to the Material Safety Data Sheet as the primary source of health and safety information.

SHELF LIFE

If >36 months from manufacture, please submit sample to Cookson Electronics Assembly Materials for testing.